Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**Top Material: Al**

**Backside Material: SiNi**

**Bond Pad Size: .0034” X .0034”**

**Backside Potential: GND**

**Mask Ref: LS161C**

**APPROVED BY: DK DIE SIZE .074” X .084” DATE: 8/29/22**

**MFG: TEXAS INSTRUMENTS THICKNESS .025” P/N: 54LS161**

**DG 10.1.2**

#### Rev B, 7/19/02